#### RC4558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIER

SLOS073D - MARCH 1976 - REVISED SEPTEMBER 2004

- Continuous Short-Circuit Protection
- Wide Common-Mode and Differential Voltage Ranges
- No Frequency Compensation Required
- Low Power Consumption
- No Latch-Up
- Unity-Gain Bandwidth . . . 3 MHz Typ
- Gain and Phase Match Between Amplifiers
- Low Noise . . . 8 nV/√Hz Typ at 1 kHz

# 10UT [ 1 8 ] V<sub>CC</sub>+ 1IN- [ 2 7 ] 20UT 1IN+ [ 3 6 ] 2INV<sub>CC</sub>- [ 4 5 ] 2IN+

D, DGK, P, PS, OR PW PACKAGE

#### description/ordering information

The RC4558 device is a dual general-purpose operational amplifier, with each half electrically similar to the  $\mu$ A741, except that offset null capability is not provided.

The high common-mode input voltage range and the absence of latch-up make this amplifier ideal for voltage-follower applications. The device is short-circuit protected, and the internal frequency compensation ensures stability without external components.

#### **ORDERING INFORMATION**

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	MSOP/VSSOP (DGK)	Reel of 2500	RC4558DGKR	YR_‡
	PDIP (P)	Tube of 50	RC4558P	RC4558P
	2010 (D)	Tube of 75	RC4558D	DO4550
0°C to 70°C	SOIC (D)	Reel of 2500	RC4558DR	RC4558
	SOP (PS)	Reel of 2000	RC4558PSR	R4558
	TSSOP (PW)	Tube of 150	RC4558PW	R4558
	1350P (PW)	Reel of 2000	RC4558PWR	K4000
	MSOP/VSSOP (DGK)	Reel of 2500	RC4558IDGKR	YS_‡
	PDIP (P)	Tube of 50	RC4558IP	RC4558IP
40°C to 95°C	2010 (D)	Tube of 75	RC4558ID	D.45501
−40°C to 85°C	SOIC (D)	Reel of 2500	RC4558IDR	R4558I
	TSSOD (DW)	Tube of 150	RC4558IPW	R4558I
	TSSOP (PW)	Reel of 2000	RC4558IPWR	K40001

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

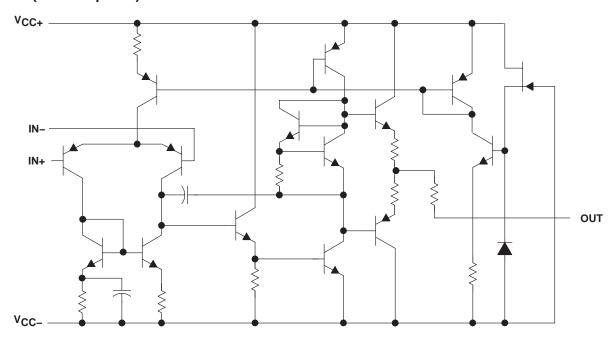


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<sup>&</sup>lt;sup>‡</sup>The actual top-side marking has one additional character that designates the assembly/test site.

#### schematic (each amplifier)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (see Note 1): V <sub>CC+</sub>		18 V
V <sub>CC</sub>		–18 V
Differential input voltage, V <sub>ID</sub> (see Note 2)		±30 V
Input voltage, V <sub>I</sub> (any input, see Notes 1 and 3)		±15 V
Duration of output short circuit to ground, one amplifie	r at a time (see Note 4)	Unlimited
Package thermal impedance, θ <sub>JA</sub> (see Notes 5 and 6)	: D package	97°C/W
	DGK package	172°C/W
	P package	85°C/W
	PS package	95°C/W
	PW package	149°C/W
Operating virtual junction temperature, T <sub>J</sub>		150°C
Storage temperature range, T <sub>stg</sub>		65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V<sub>CC+</sub> and V<sub>CC-</sub>.
  - 2. Differential voltages are at IN+ with respect to IN-.
  - 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
  - 4. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
  - 5. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  - 6. The package thermal impedance is calculated in accordance with JESD 51-7.



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#### recommended operating conditions

			MIN	MAX	UNIT
VCC+	Complements		5	15	V
VCC-	Supply voltage	-5	-15	٧	
т.	eveting free cir temperature	RC4558	0	70	00
TA	Operating free-air temperature	-40	85	°C	

# electrical characteristics at specified free-air temperature, $V_{CC+}$ = 15 V, $V_{CC-}$ = -15 V

	PARAMETER		TEST COND	ITIONS†	MIN	TYP	MAX	UNIT
				25°C		0.5	6	
V <sub>IO</sub>	Input offset voltage		$V_O = 0$	Full			7.5	mV
				range			7.5	
				25°C		5	200	
liO	Input offset current		AO = 0	Full			300	nA
				range				
				25°C		150	500	
I <sub>IB</sub>	Input bias current		VO = 0	Full			800	nA
				range				
VICR	Common-mode input voltage range			25°C	±12	±14		V
			$R_L = 10 \text{ k}\Omega$	25°C	±12	±14		
Vом	Maximum output voltage swing		25°C	±10	±13		V	
Olvi	3	$R_L = 2 k\Omega$	Full	±10				
			range					
			$R_L \ge 2 k\Omega$ ,	25°C	20	300		V/mV
AVD	Large-signal differential voltage amplification	$V_0 = \pm 10 \text{ V}$	Full	15				
B <sub>1</sub>	Unity-gain bandwith			range 25°C		3		MHz
	Input resistance			25°C	0.3	5		MΩ
r <sub>i</sub> CMRR	'			25°C	70	90		dB
CIVIRK	Common-mode rejection ratio		\/ \  \  \  \  \  \  \  \  \  \  \  \  \	25°C	70	90		иь
ksvs	Supply-voltage sensitivity ( $\Delta V_{IO}/\Delta V_{CC}$ )		$V_{CC} = \pm 15 \text{ V}$ to $\pm 9 \text{ V}$	25°C		30	150	μV/V
V <sub>n</sub>	Equivalent input noise voltage (closed loop)	$A_{VD} = 100,$ $R_{S} = 100  \Omega,$	25°C		8		nV/√ <del>Hz</del>	
		f = 1 kHz, BW = 1 Hz						
			., .	25°C		2.5	5.6	
ICC	Supply current (both amplifiers)		V <sub>O</sub> = 0, No load	T <sub>A</sub> (min)		3	6.6	mA
		No load	T <sub>A(max)</sub>		2.3	5		
PD			V <sub>O</sub> = 0, No load	25°C		75	170	mW
	Total power dissipation	T <sub>A(min)</sub>			90	200		
_	(both amplifiers)	140 loau	T <sub>A(max)</sub>		70	150		
	One and all and a constitute	Open loop	$R_S = 1 k\Omega$ ,			85		
V <sub>O1</sub> /V <sub>O2</sub>	Crosstalk attenuation	A <sub>VD</sub> = 100	f = 10 kHz	25°C		105		dB

<sup>†</sup> All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified. Full range is 0°C to 70°C for RC4558 and -40°C to 85°C for RC4558I.

# operating characteristics, $V_{CC+}$ = 15 V, $V_{CC-}$ = -15 V, $T_A$ = 25°C

	PARAMETER		TEST CONDITI	ONS	MIN	TYP	MAX	UNIT
t <sub>r</sub>	Rise time	$V_{I} = 20 \text{ mV},$	$R_L = 2 k\Omega$ ,	C <sub>L</sub> = 100 pF		0.13		ns
	Overshoot	$V_{I} = 20 \text{ mV},$	$R_L = 2 k\Omega$ ,	C <sub>L</sub> = 100 pF		5		%
SR	Slew rate at unity gain	V <sub>I</sub> = 10 V,	$R_L = 2 k\Omega$ ,	C <sub>L</sub> = 100 pF	1.1	1.7		V/μs









#### **PACKAGING INFORMATION**

Orderable	Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp (3)
RC45	58D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
RC4558	DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
RC455	8DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC455	58ID	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
RC4558I	DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
RC455	8IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
RC455	58IP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
RC4558	8IPW	ACTIVE	TSSOP	PW	8	150	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
RC4558	IPWR	ACTIVE	TSSOP	PW	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
RC45	58P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
RC4558	PSLE	OBSOLETE	SO	PS	8		None	Call TI	Call TI
RC4558	BPSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
RC455	8PW	ACTIVE	TSSOP	PW	8	150	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
RC4558	PWLE	OBSOLETE	TSSOP	PW	8		None	Call TI	Call TI
RC4558	BPWR	ACTIVE	TSSOP	PW	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
RC45	58Y	OBSOLETE	XCEPT	Υ	0		None	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

None: Not yet available Lead (Pb-Free).

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<sup>(2)</sup> Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.



## **PACKAGE OPTION ADDENDUM**

18-Feb-2005

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#### P (R-PDIP-T8)

#### PLASTIC DUAL-IN-LINE



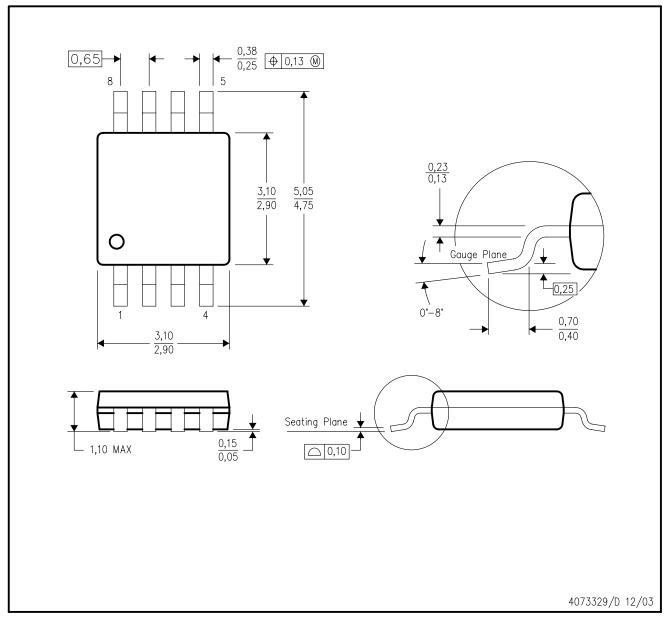
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg\_info.htm

# DGK (S-PDSO-G8)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187 variation AA.



# D (R-PDSO-G8)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



#### PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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